For assistance or to order; call (800) 531-5782

Series 78**S**T200

2 AMP POSITIVE STEP-DOWN **INTEGRATED SWITCHING REGULATOR**

Revised 6/30/98





C1 = Optional 1µF ceramic C2 = Required 100µF electrolytic

Specifications







V = Vertical Mount **S** = Surface Mount **H** = Horizontal Mount

(For dimensions and PC board layout see Package Style 500.)

Characteristics			78ST200			
$(T_a = 25^{\circ}C \text{ unless noted})$	Symbols	Conditions	Min	Тур	Max	Units
Output Current	Io	Over V _{in} range	0.1*	_	2.0	А
Input Voltage Range	Vin	$I_o = 0.1 \text{ to } 3.0 \text{A}$ $V_o < 3.5 \text{V}$ $V_o = 5.0 \text{V}$	7 8	=	15 20	V V
Output Voltage Tolerance	ΔV_o	Over V_{in} range, $I_o = 2.0A$ $T_a = 0^{\circ}C$ to +60°C	—	±1.0	±2.0	%Vo
Line Regulation	Reg _{line}	Over V _{in} range	_	±0.4	±0.8	$%V_{o}$
Load Regulation	Regload	$0.1 \leq I_o \leq 2.0A$	_	±0.2	±0.4	%Vo
Ripple/Noise	Vn	$V_{in} = V_{in} \min$, $I_o = 2.0A$		1	_	%Vo
Transient Response (with 100µF output cap)	t _{tr}	50% load change V _o over/undershoot	—	100 5.0	—	μSec %Vo
Efficiency	η	$V_{in} = 9V, I_o = 2.0A, V_o = 5V$	_	82	_	%
Switching Frequency	$f_{ m o}$	Over V _{in} and I _o ranges	0.95	1.0	1.05	MHz
Absolute Maximum Operating Temperature Range	T _a	_	-40	-	+85	°C
Recommended Operating Temperature Range	Ta	Free Air Convection, (40-60LFM) Over V_{in} and I_o ranges	-40	_	+85**	°C
Thermal Resistance	θ_{ja}	Free Air Convection, (40-60LFM)	_	38	—	°C/W
Storage Temperature	Ts	_	-40	_	+125	°C
Mechanical Shock	_	Per Mil-STD-883D, Method 2002.3	_	500	_	Gʻs
Mechanical Vibration	—	Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board	_	5	_	Gʻs
Weight			_	7	_	Grams

* ISR will operate down to no load with reduced specifications.

** See Thermal Derating chart.

Note: The 78ST200 Series requires a 100µF electrolytic or tantalum output capacitor for proper operation in all applications.

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78ST200 Seri

CHARACTERISTIC DATA



Note 1: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25°C. This data is considered typical data for the ISR. Note 2: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM. (See Thermal Application Note)

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins I	Package Qtv	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
78ST205HC	NRND	SIP MOD ULE	EFA	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST205SC	NRND	SIP MOD ULE	EFC	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST205SCT	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST205VC	NRND	SIP MOD ULE	EFD	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST233HC	NRND	SIP MOD ULE	EFA	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST233SC	NRND	SIP MOD ULE	EFC	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST233VC	NRND	SIP MOD ULE	EFD	3	25	TBD	Call TI	Level-1-215C-UNLIM
78ST235HC	NRND	SIP MOD ULE	EFA	3		TBD	Call TI	Call TI
78ST235SC	OBSOLETE	SIP MOD ULE	EFC	3		TBD	Call TI	Call TI
78ST235VC	OBSOLETE	SIP MOD ULE	EFD	3		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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